



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



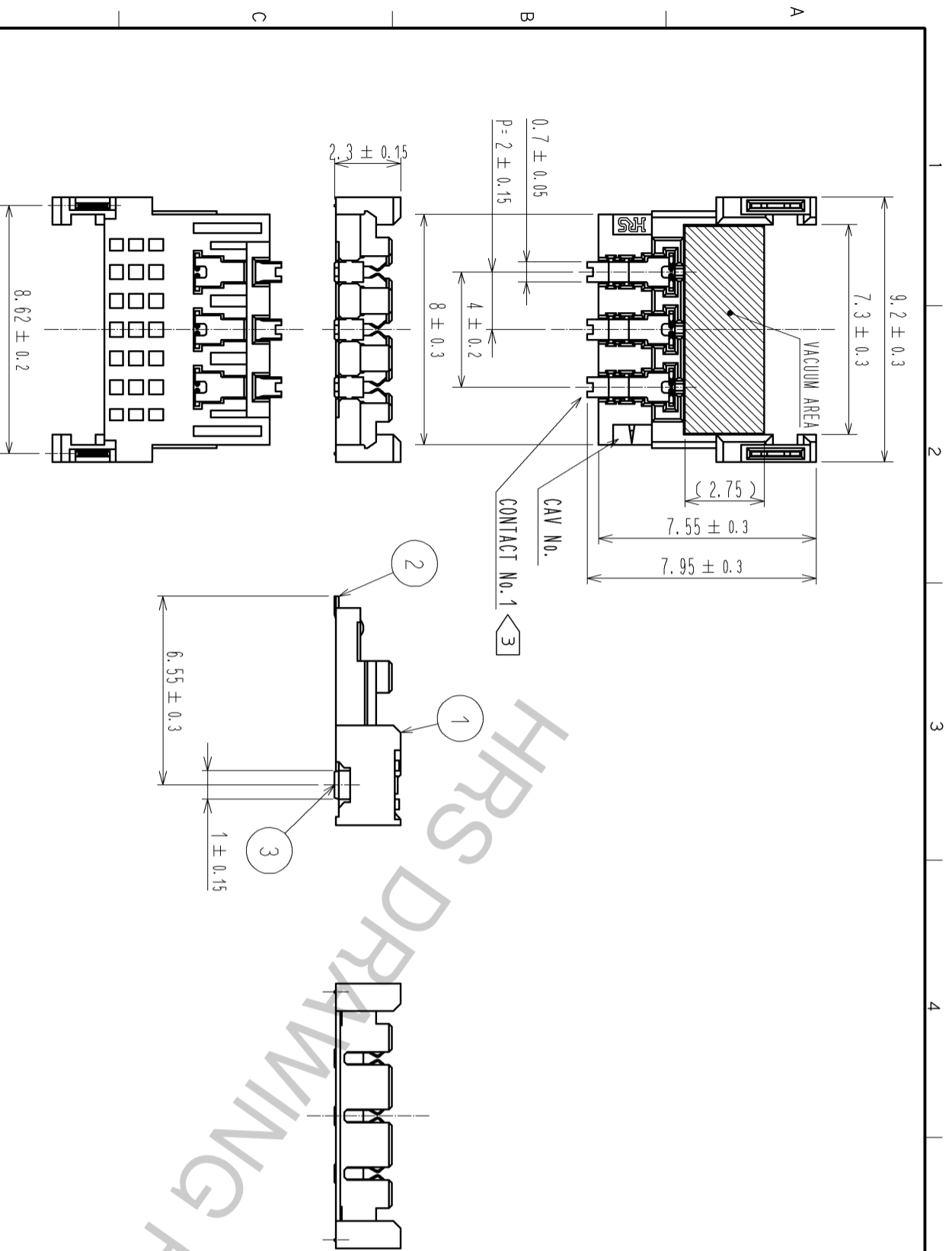
Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

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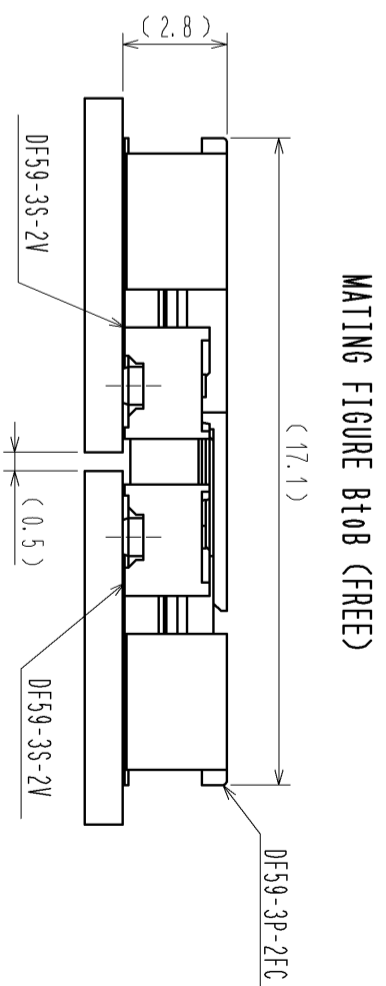
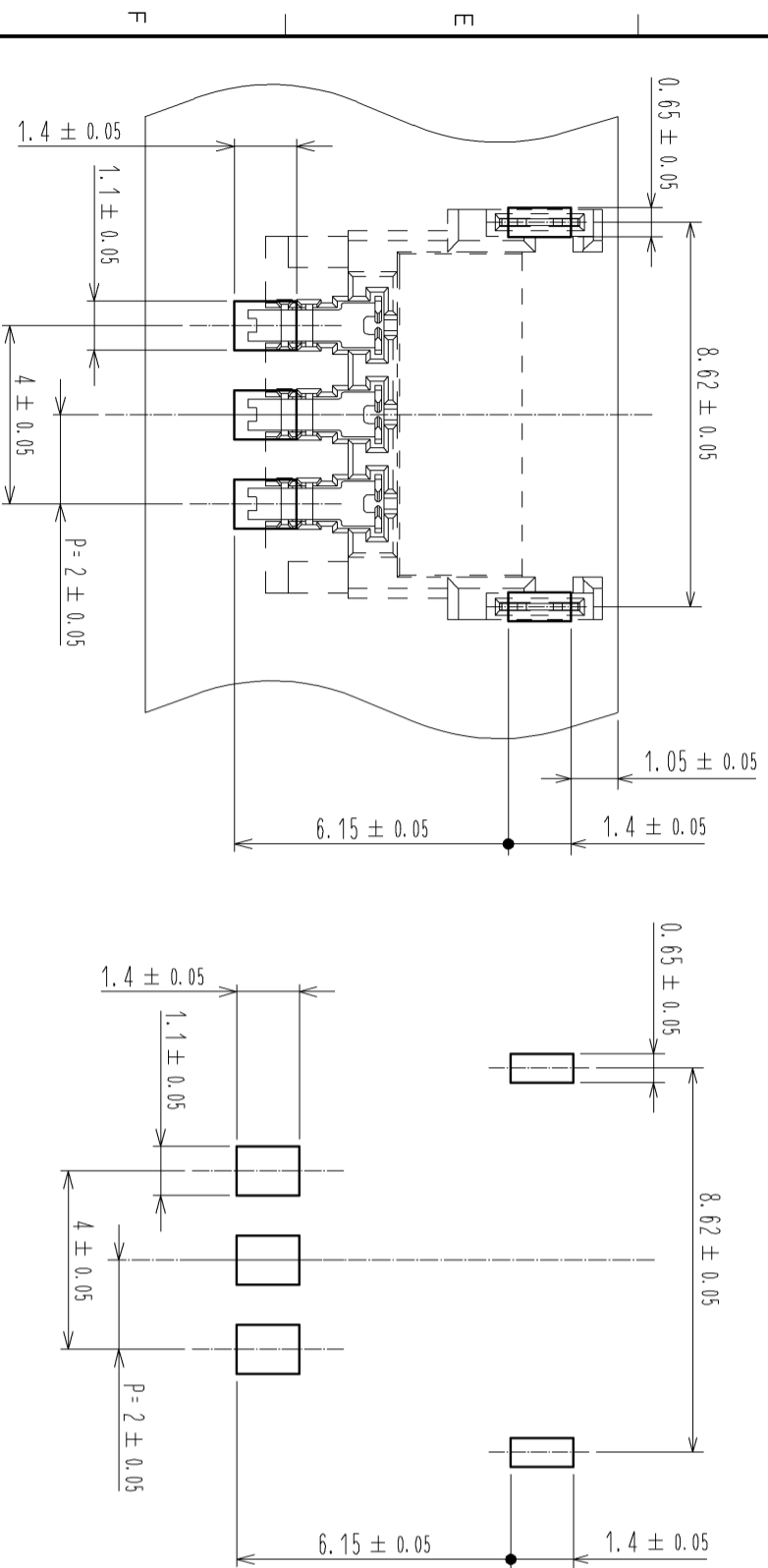
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



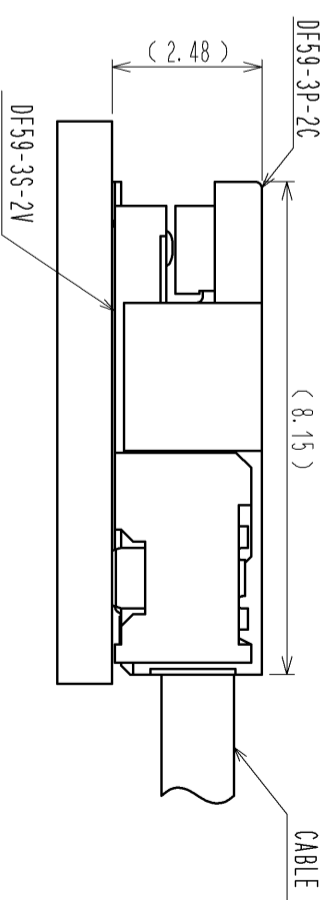


RECOMMENDED PCB LAYOUT (FREE)

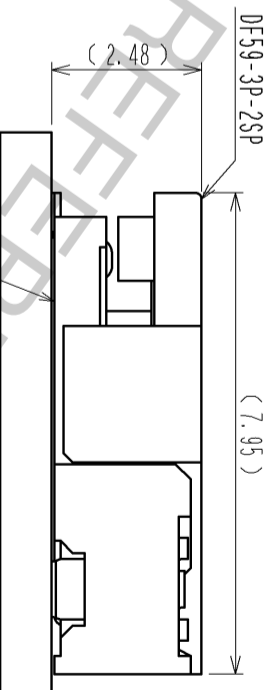
RECOMMENDED PCB LAYOUT (FREE)



MATING FIGURE Wt0B (FREE)



MATING FIGURE Bt0SP (FREE)



MATING FIGURE Bt0B (FREE)

- NOTE1. LEAD CO-PLANARITY SHALL BE 0.1mm MAX.
 2. () IS REFERENCE DIMENSION.
 3. MATING DF59-3P-2C, DF59-3P-2SP ARE APPLIED.
 4. REFER TO THE DF59 SERIES MATING/UMATING OPERATION INSTRUCTION MANUAL(ETAD-H0496)
 FOR THE OPERATING OF THE PRODUCT.
 5. UL(FILE NO. E52653),
 C-UL(FILE NO. E52653) APPROVED PRODUCT.



NO.	MATERIAL	FINISH	REMARKS	NO.	MATERIAL	FINISH	REMARKS
1	LCP	UL94V-0/BEIGE		3	PHOSPHOR BRONZE		UNDER PLATING : NICKEL PLATING 05μm MIN
2	PHOSPHOR BRONZE		CONTACT AREA : GOLD PLATING 0.2μm MIN LEAD AREA : TIN PLATING 1μm MIN UNDER PLATING : NICKEL PLATING 05μm MIN	4	PS		CLEAR/EMBOSSED CARRIER TAPE)
				5	POLYESTER		CLEARCOVER TAPE)
				6	PS		REEL , BLACK

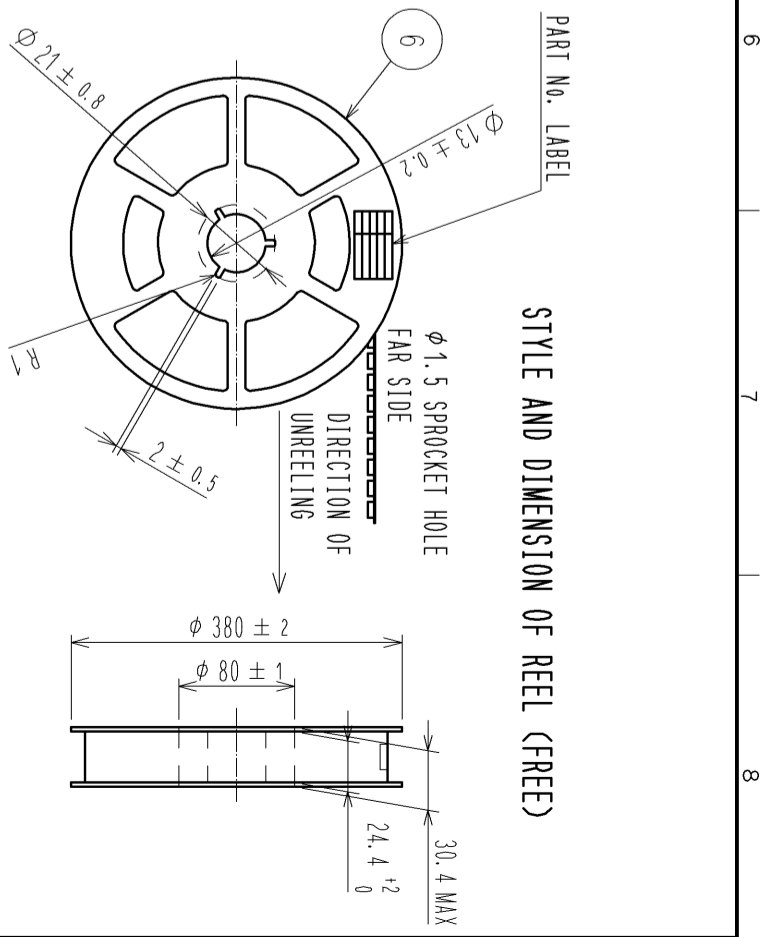
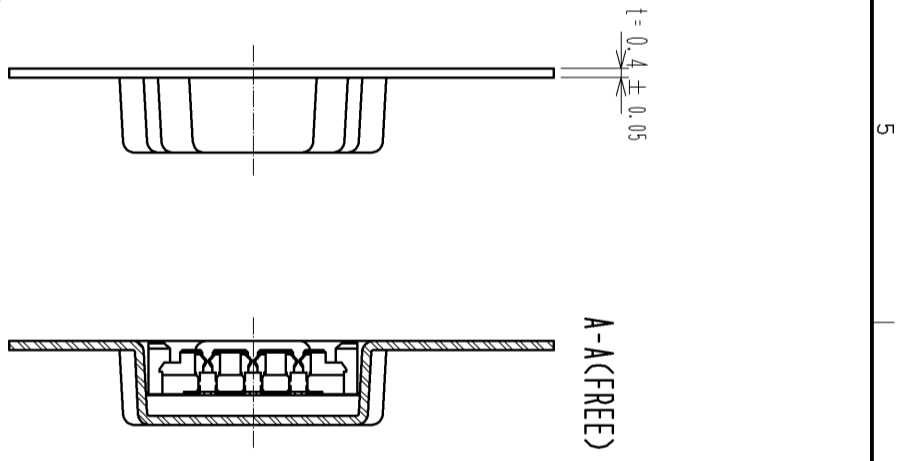
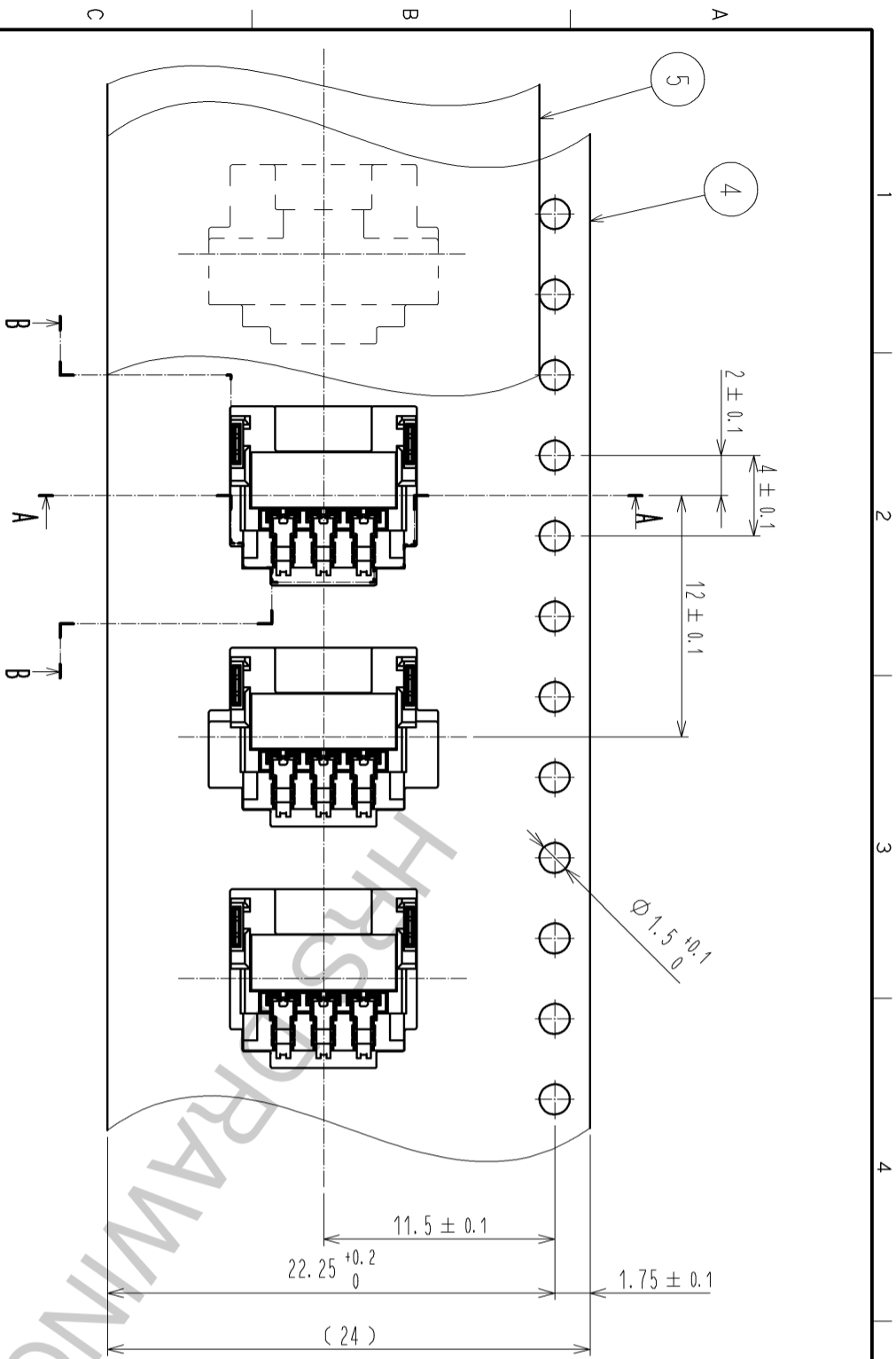
UNITS	SCALE	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm	5 : 1	5	DIS-H-006828	MI. SAKIMURA	HK. UMEHARA	12.04.20

NO.	DESIGNED	CHECKED	DATE
1	KT. ISHII	KT. ISHII	10.09.27
2	KT. ISHII	KT. ISHII	10.09.27
3	KT. ISHII	KT. ISHII	10.09.27

NO.	DESIGNED	CHECKED	DATE
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3	KT. ISHII	KT. ISHII	10.09.27

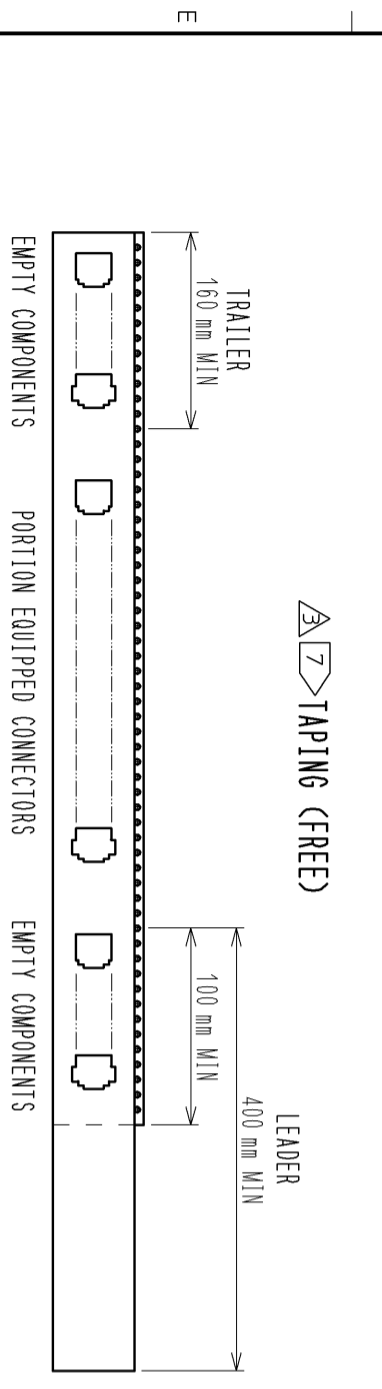
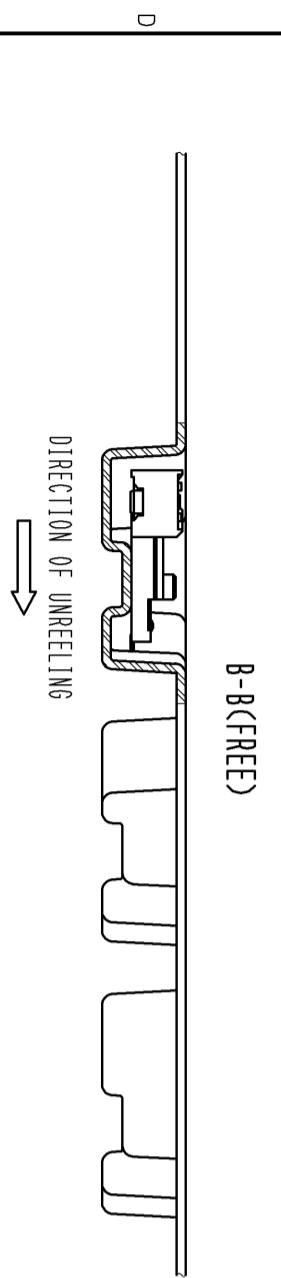
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3	KT. ISHII	KT. ISHII	10.09.27

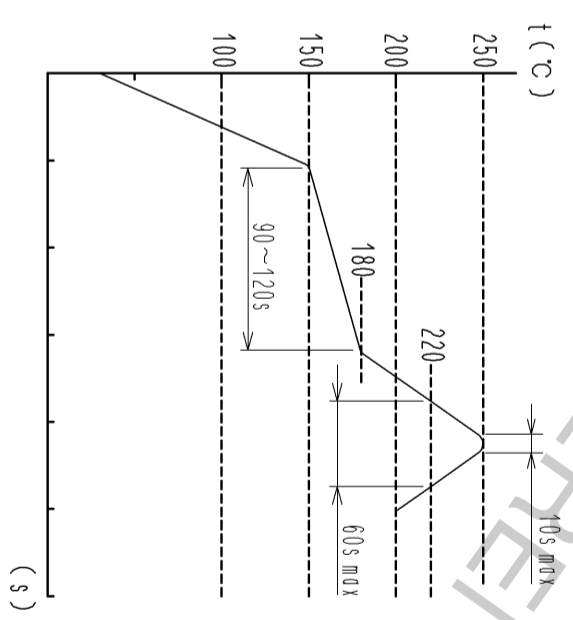


DETAIL OF PART No. LABEL

生産日	年月日
図番	CL667-0002-3-51
品名	DF59-3S-2V(51)
納入数量	2000 K0
納入者	ヒロセ電機(株)
SUPPLIER	
QUANTITY	
PART No.	
CODE No.	
DATE OF MANUFACTURED	



NOTE: 6 REEL : 2000 CONNECTORS
 REEL TO JIS C 0806. (PACKAGING OF COMPONENTS FOR AUTOMATING HANDLING)
 THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCE.



REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE (REFERENCE)

NUMBER OF REFLOW CYCLES 2 CYCLES MAX.
 THE TEMPERATURE IS MEASURED IN THE TERMINAL LEAD PART.
 ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE,
 PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT
 THE PROFILE. THEREFORE, A THOROUGH EVALUATION OF
 MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION.
 TEMPERATURE IS MEASURED AT CONTACT LEAD.

FORM HC0011-5-8

DRAWING NO.	EDC3-330589-01
PART NO.	DF59-3S-2V(C51)
CODE	CL667-0002-3-51

HRS